



Material Content Data Sheet



Sales Product Name		IFX30081LD V33		Issued		23. January 2018		
MA#		MA001839806						
Package		PG-TSON-10-2		Weight*		31.71 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.996	3.14	3.14	31413	31413
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		105	
	non noble metal	zinc	7440-66-6	0.013	0.04		418	
	non noble metal	iron	7439-89-6	0.265	0.84		8368	
wire	non noble metal	copper	7440-50-8	10.773	33.98	34.87	339769	348660
	non noble metal	copper	7440-50-8	0.022	0.07	0.07	690	690
	encapsulation	organic material	carbon black	1333-86-4	0.038	0.12		1185
encapsulation	plastics	epoxy resin	-	1.935	6.10		61035	
	inorganic material	silicondioxide	60676-86-0	16.815	53.04	59.26	530354	592574
leadfinish	non noble metal	tin	7440-31-5	0.370	1.17	1.17	11673	11673
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2027	2027
glue	plastics	epoxy resin	-	0.103	0.32		3241	
	noble metal	silver	7440-22-4	0.308	0.97	1.29	9722	12963
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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